DATA SHEET

OCMOS FET PS7141E-1A,PS7141EL-1A

6-PIN DIP, 400V BREAK DOWN VOLTAGE NORMALLY OPEN TYPE 1-ch Optical Coupled MOS FET

-NEPOC Series-

Solid State Relay

DESCRIPTION

EL

The PS7141E-1A and PS7141EL-1A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity. The PS7141EL-1A has a surface mount type lead.

FEATURES

- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- Ordering number of taping product: PS7141EL-1A-E3, E4: 1 000 pcs/reel
- Pb-Free product
- <R> Safety standards

<R>

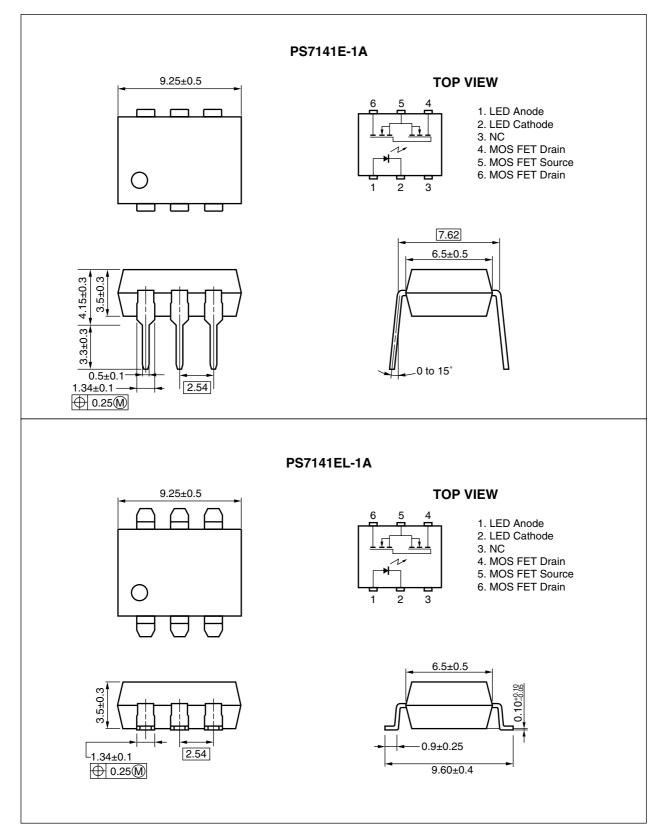
- UL approved: File No. E72422
- BSI approved: No. 8806/8807
- SEMKO approved: No. 313447
- DEMKO approved: No. 312887
- NEMKO approved: No. P4202453
- FIMKO approved: No. FI 20732

APPLICATIONS

- Exchange equipment
- · Measurement equipment
- FA/OA equipment

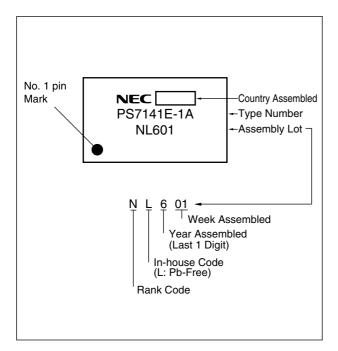
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PACKAGE DIMENSIONS (in millimeters)



NEC

<R> MARKING EXAMPLE



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS7141E-1A	PS7141E-1A-A	Pb-Free	Magazine case 50 pcs	Standard products	PS7141E-1A
PS7141EL-1A	PS7141EL-1A-A			(UL, BSI, SEMKO,	
PS7141EL-1A-E3	PS7141EL-1A-E3-A		Embossed Tape 1 000 pcs/reel	DEMKO, NEMKO,	
PS7141EL-1A-E4	PS7141EL-1A-E4-A			FIMKO approved)	

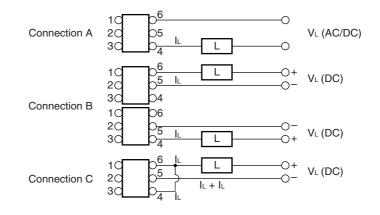
*1 For the application of the Safety Standard, following part number should be used.

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)		lf	50	mA
	Reverse Voltage		VR	5.0	V
	Power Dissipation		PD	50	mW
	Peak Forward Current ¹		IFP	1	А
MOS FET	DS FET Break Down Voltage		VL	400	V
	Continuous	Connection A	IL.	120	mA
	Load Current ^{*2}	Connection B		150	
		Connection C		250	
	Pulse Load Current ^{*3} (AC/DC Connection)		Ilp	240	mA
	Power Dissipation		PD	560	mW
Isolation Voltage ⁴		BV	1 500	Vr.m.s.	
Total Powe	Total Power Dissipation		Р⊤	610	mW
Operating A	Operating Ambient Temperature		TA	-40 to +85	°C
Storage Te	Storage Temperature		Tstg	-40 to +100	°C

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

*1 PW = 100 *µ*s, Duty Cycle = 1%

*2 Conditions: IF \geq 5 mA. The following types of load connections are available.



*3 PW = 100 ms, 1 shot

*4 AC voltage for 1 minute at $T_A = 25^{\circ}$ C, RH = 60% between input and output Pins 1-3 shorted together, 4-6 shorted together.

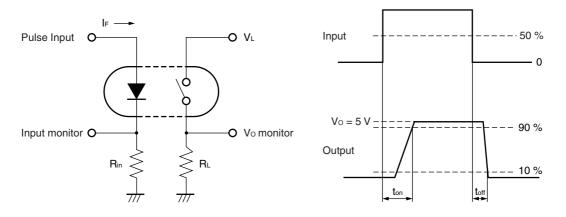
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	5	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

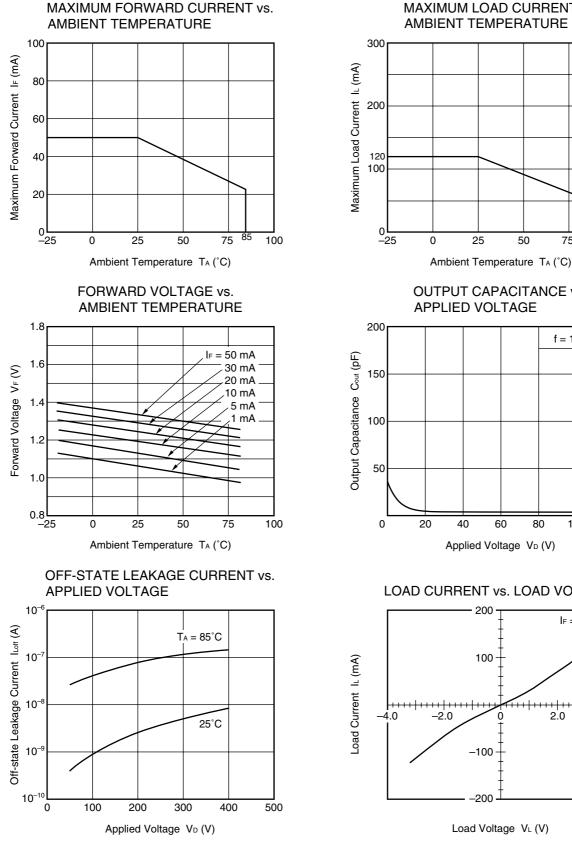
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	IR	$V_{R} = 5 V$			5.0	μA
MOS FET	Off-state Leakage Current	ILoff	V _D = 400 V		0.01	1.0	μA
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		36		pF
Coupled	LED On-state Current	IFon	l∟ = 120 mA			5.0	mA
	On-state Resistance	Ron1	I⊧ = 10 mA, I∟ = 10 mA		36	50	Ω
		Ron2	I_{F} = 10 mA, I_{L} = 120 mA, $t \leq$ 10 ms		25	35	
	Turn-on Time ^{*1, 2}	ton	$I_F = 10 \text{ mA}, \text{ V}_0 = 5 \text{ V}, \text{ R}_L = 1.5 \text{ k}\Omega,$		0.5	1.0	ms
	Turn-off Time ^{*1, 2}	toff	PW ≥ 10 ms		0.07	0.2	
	Isolation Resistance	R⊦o	VI-O = 1.0 kVDC	10 [°]			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1 MHz		1.1		pF

*1 Test Circuit for Switching Time

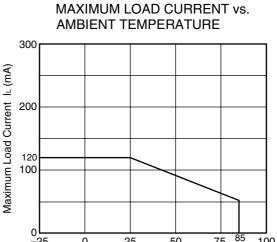


*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
 Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)



Remark The graphs indicate nominal characteristics.



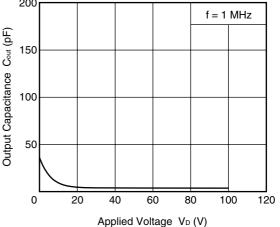
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OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

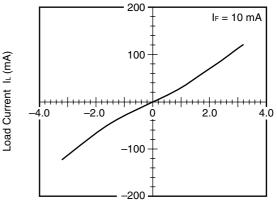
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75

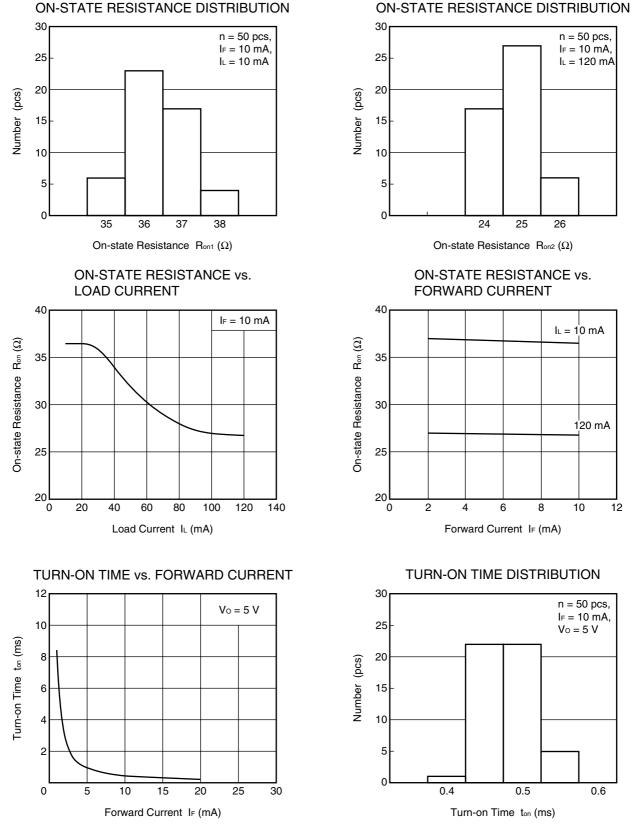
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LOAD CURRENT vs. LOAD VOLTAGE

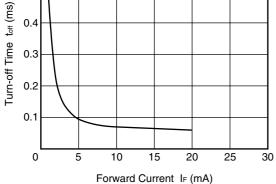


Load Voltage VL (V)

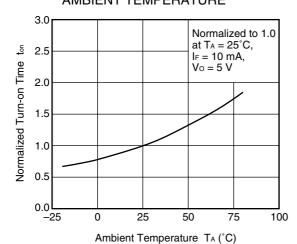


Remark The graphs indicate nominal characteristics.

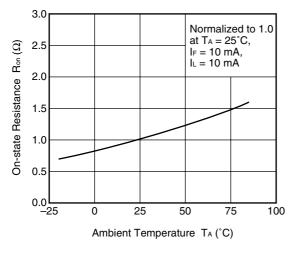
TURN-OFF TIME vs. FORWARD CURRENT 0.6 0.5 0.5 0.4



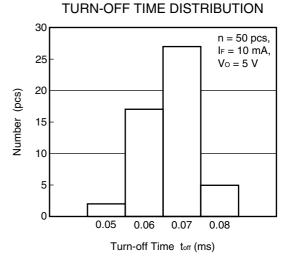




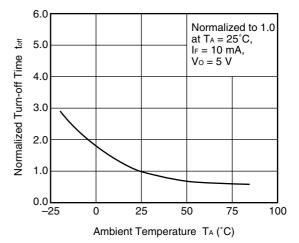




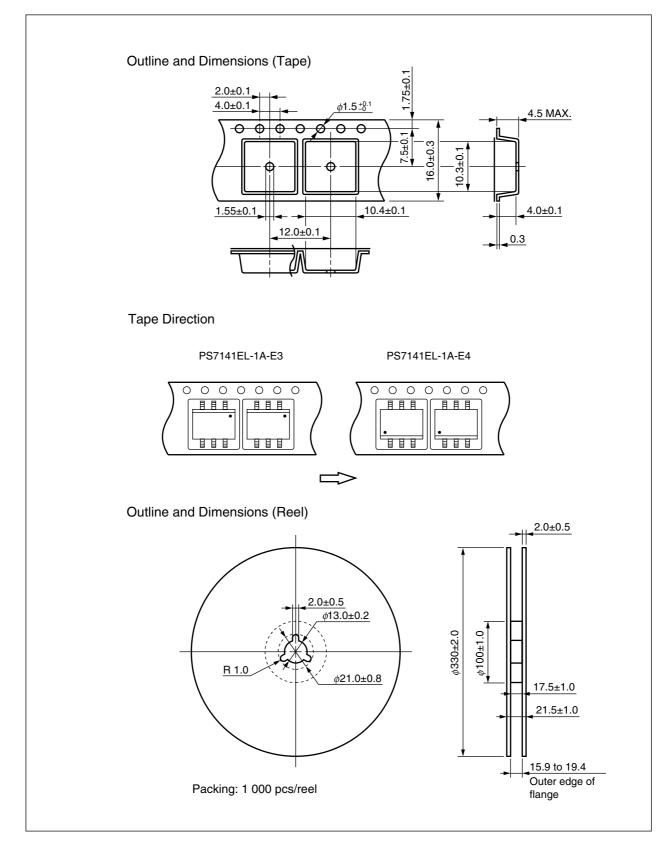
Remark The graphs indicate nominal characteristics.



NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



TAPING SPECIFICATIONS (in millimeters)



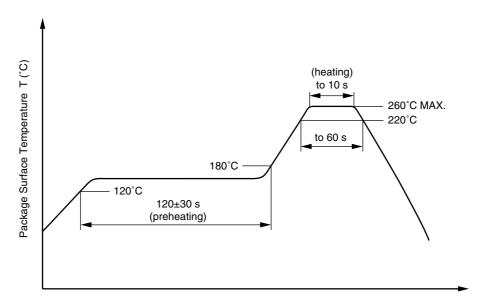
RECOMMENDED SOLDERING CONDITIONS

- (1) Infrared reflow soldering
 - Peak reflow temperature
 - Time of peak reflow temperature
 - Time of temperature higher than 220°C
 - Time to preheat temperature from 120 to 180°C
 - Number of reflows
 - Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

 Temperature 	260°C or below (molten solder temperature)
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- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times
- Flux

One Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

350°C or below
3 seconds or less
Rosin flux containing small amount of chlorine (The flux with a
maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- **1.** Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	 Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	• Do not lick the product or in any way allow it to enter the mouth.

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